

Connector for CMOS Camera Module

SCKA Series



Compact size achieved from thin body-forming molding.

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
W-SIM

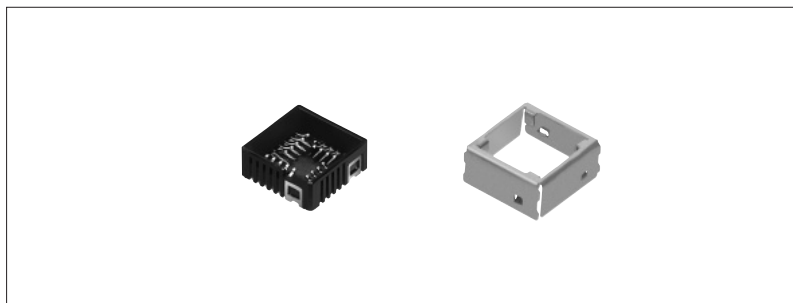
For
Memory
Stick Micro™

For
Memory
Stick™

Combine Type

For
Compact
Flash™

For CMOS
Camera Module



Typical Specifications

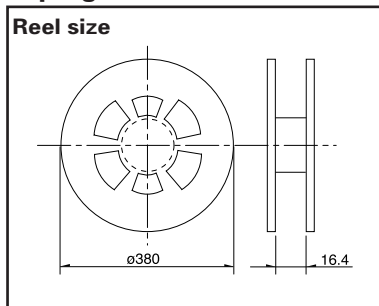
Items		Specifications
Dimensions	6×6mm module type	7×7×3.1mm
Structure	Mounting system	Surface mounting type
Performance	Operating temperature range	−25℃ to +85℃
	Voltage proof	100V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycles	10cycles

Product Line

Items	Product	Packing system	Minimum packing unit (pcs.)	Product No.	Drawing No.
6×6mm module type	Connector	Taping	2,000	SCKA2A0100	1
	Cover	—	5,000	JSCKA0002A	2

Packing Specifications

Taping Unit:mm



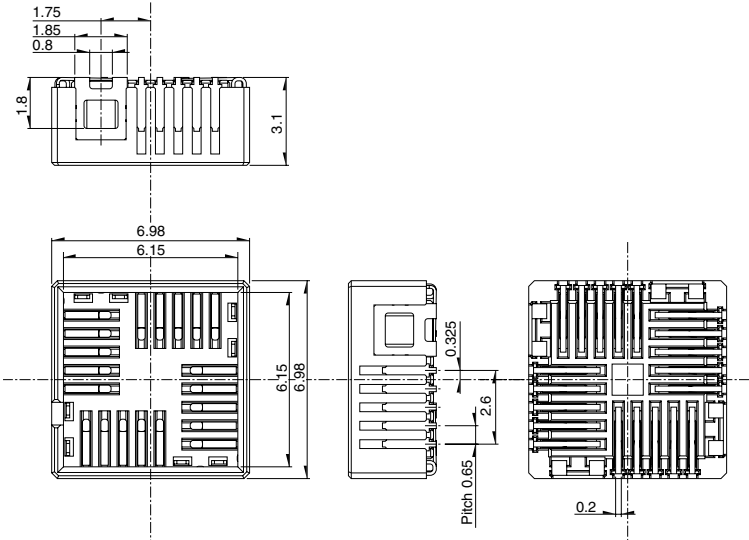
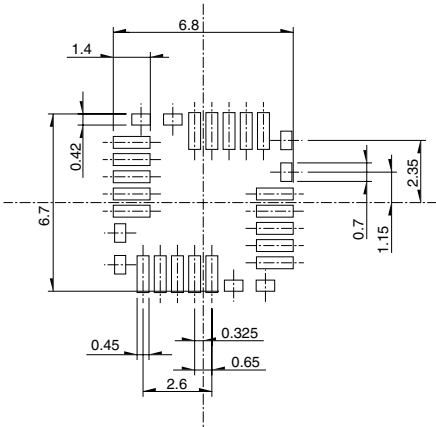
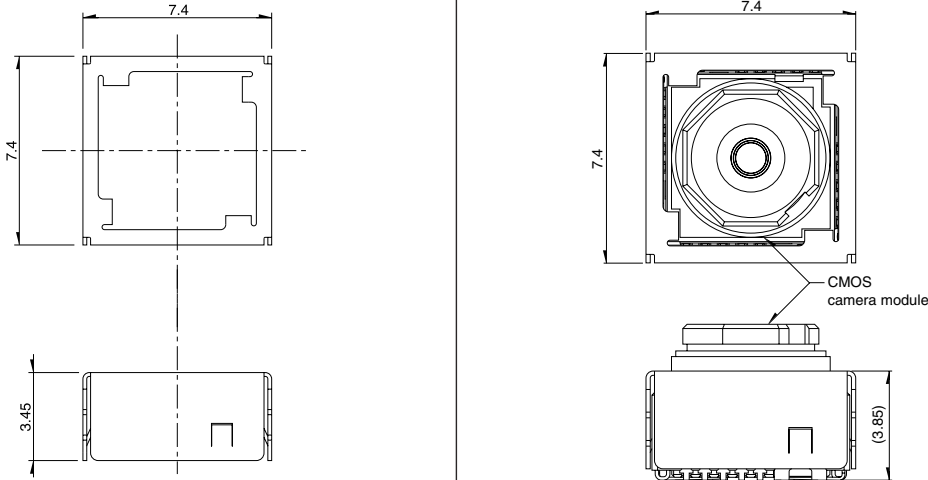
Product No.	Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing		
SCKA2A0100	2,000	4,000	12,000	16	420×410×187

Bulk

Product No.	Number of packages (pcs.)		Export package measurements (mm)
	1 case /Japan	1 case /export packing	
JSCKA0002A	5,000	10,000	400×288×161

■ Dimensions
6×6mm module type

Unit:mm

No.	Style	
1	Connector	
	PC board mounting hole dimensions (Viewed from the mounting face side)	
		
2	Style	Connector/Cover combination diagram (Reference)
	Cover	

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Combine Type

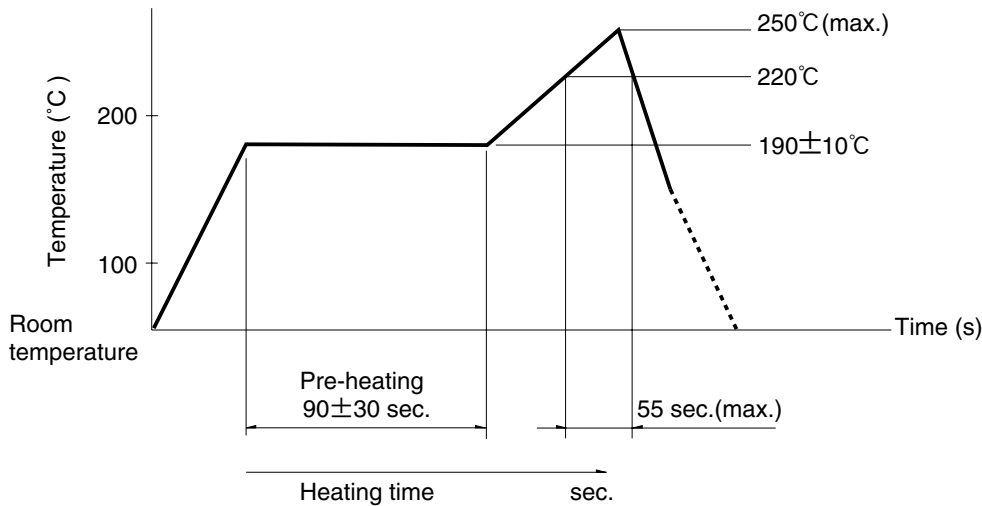
For
Compact
Flash™

For CMOS
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
3. Temperature profile



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.